



SMJ 500-3B

Quad-Diode Mixer

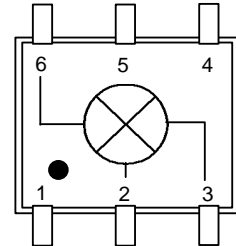
The Communications Edge™

Preliminary Product Information

Product Features

- Input IP3 +11 dBm
- RF Freq 2 - 500 MHz
- LO Freq 2 - 500 MHz
- IF Freq DC - 500 MHz
- LO Drive Level +3 dBm

Functional Diagram



| Function | Pin No. |
|----------|---------|
| Ground | 1 |
| IF | 2 |
| RF | 3 |
| Ground | 4-5 |
| LO | 6 |

Specifications

| Parameters | Units | Minimum | Typical | Maximum | Comments |
|---------------------|-------|---------|---------|---------|----------|
| RF Frequency | MHz | 2 | | 500 | |
| LO Frequency | MHz | 2 | | 500 | |
| IF Frequency | MHz | DC | | 500 | |
| SSB Conversion Loss | dB | | 6.0 | | |
| L-R Isolation | dB | | 32 | | |
| L-I Isolation | dB | | 30 | | |
| IIP3 | dBm | | +11 | | |
| LO Drive | dBm | | +3 | | |
| RF - Return Loss | dB | | 11 | | |
| LO - Return Loss | dB | | 14 | | |
| IF - Return Loss | dB | | 11 | | |

Test conditions unless otherwise noted
 1. Tested in a 50 Ohm System, low Side LO.

Recommended Maximum Rating

| Parameters | Rating |
|-------------------------------------|----------------|
| Operating Case Temperature | -40 to +70 °C |
| Storage Temperature | -65 to +100 °C |
| RF Input Power at 25°C (continuous) | +10 dBm |

Ordering Information

| Part No. | Description |
|----------------|---|
| SMJ 500-3B | Diode Mixer (Available in Tape & Reel) |
| SMJ 500-3B-PCB | Fully Assembled Application Circuit |

This document contains information on a new product.
 Specifications and information are subject to change without notice



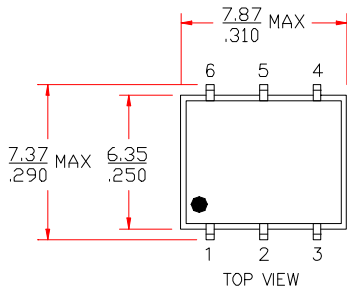
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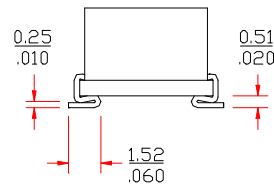
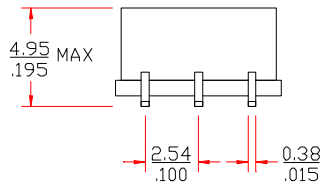
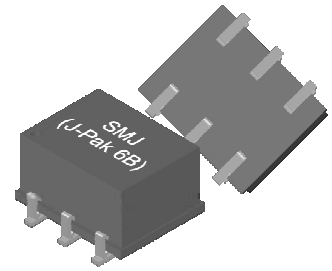
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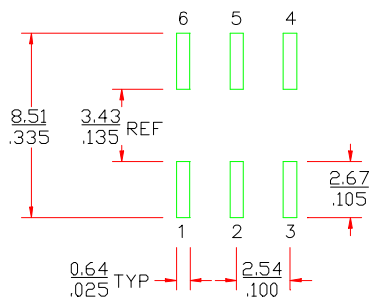
OUTLINE DRAWING



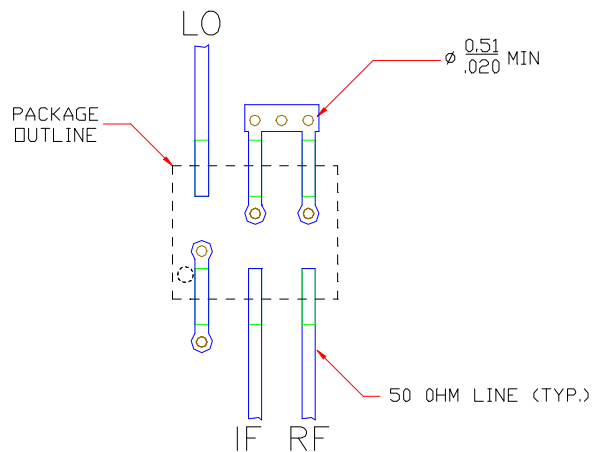
mm
inch



LAND PATTERN



MOUNTING CONFIGURATION



| FUNCTION | PIN NO. |
|----------|---------|
| GROUND | 1 |
| IF | 2 |
| RF | 3 |
| GROUND | 4-5 |
| LO | 6 |

- Notes:
1. Ground vias are critical for RF grounding considerations.
 2. If your PCB design rules allow, ground vias should be placed under the land pattern for better RF performance. Otherwise ground vias should be placed as close land pattern as possible.
 3. Trace width depends on PC board.

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